Inventor: Scott Schaefer Serial No.: 10/669,663

## In the Claims

1. (presently amended) A method of operating an electronic device having a plurality of memory devices dice, each memory device die having at least two sub-arrays therein, the method comprising:

individually addressing each sub-array of each said memory device die by communicating an address specific to that sub-array across an address bus coupled to all said memory devices dice, and by individually selecting said individual memory device die from among said plurality of memory devices dice, while the remainder of said memory dice except said individual memory die remain in a standby mode.

- 2. (presently amended) The method of claim 1, wherein said plurality of memory devices dice are formed as a part of a memory module.
- 3. (presently amended) The memory device method of claim 1, wherein said electronic device comprises a computer.
- 4. (presently amended) A method of operating an electronic device having a plurality of memory devices dice associated therewith, each memory device die having at least two sub-arrays therein, the method comprising:

individually selecting at least one individual memory device from among said plurality of memory devices; and

individually addressing — every selected sub-array of said selected memory device die by communicating an address specific to a memory cell of each that sub-array across an address bus coupled to each memory device die of said plurality of memory devices to dice; and

accessing -a one memory cell in every said selected sub-array of only said selected memory die.

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5. (presently amended) The method of claim 4, further comprising maintaining at least one memory <u>device</u> <u>die</u> of said plurality of <u>devices</u> <u>dice</u> in a standby mode, while accessing said memory cell in said selected sub-array.

- 6. (presently amended) The method of claim 4, wherein said individual selection of said at least one individual memory device die comprises decoding a plurality of activation signals to determine the memory device die to be individually selected.
- 7. (presently amended) The method of claim 4, further comprising:

selecting addressing a number of said memory devices dice from said plurality of memory devices dice; and

enabling only one die from said plurality of memory dice to accessing a number of data bits from only said selected memory die , wherein said number of data bits accessed is greater than said number of memory devices selected.

8. (presently amended) A method of configuring an electronic system having a plurality of memory devices therein, comprising:

providing a plurality of memory devices dice, each memory device die having a plurality of banks sub-arrays therein;

coupling a plurality of data lines to each memory device die, with each data line coupled to only one bank sub-array in each memory device die;

coupling an address bus to each memory device die, said address bus configured to allow access of -a- one memory cell in any bank each sub-array of said plurality of banks sub-arrays in each die of said plurality of dice said memory device; and

providing at least one chip select mechanism to facilitate individual selection of each memory device die, said system configured to allow fewer than all of said plurality of memory devices dice to be selected and activated, while the remaining memory devices dice of said plurality of memory devices dice are unselected and in a low power mode.

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9. (presently amended) The method of claim 8 wherein said memory devices dice are physically coupled to a memory module.

- 10. (original) The method of claim 8 wherein said electronic system comprises a computer.
- 11. (new) The method of claim 1 further comprising providing a memory die having only one sub-array which supplies a parity bit.
- 12. (new) The method of claim 4 further comprising providing a memory die having only one sub-array which supplies a parity bit.
- 13. (new) The method of claim 8 further comprising providing a memory die having only one sub-array which supplies a parity bit.